



## Heat Transfer Overview



## Conduction

- Energy transfer from more to less energetic particles due to particle interactions – diffusion of energy due to molecular activity
  - Examples
  - Usually involves solids
  - Rate = f( )
  - What is the driving potential?



## Fourier's Law of Heat Conduction

$$q_x = -kA \frac{dT}{dx} \quad \text{Total heat transfer in x direction}$$

$$q_x'' = \frac{q_x}{A} = -k \frac{dT}{dx} \quad \text{Heat transfer per unit area in x direction}$$

k=thermal conductivity (W/m°C or Btu/h ft °F)

-- a measure of how fast heat flows through a material

-- k(T), but we usually use the value at the average temperature

q can have x, y, and z components; it's a vector quantity



## Special Case

- If T(x) is linear, Fourier's Law for the 1-D case becomes

$$q_x'' = -k \frac{\Delta T}{\Delta x} = -k \frac{T_2 - T_1}{x_2 - x_1} = -k \frac{T_2 - T_1}{L}$$

- When will this happen?
- Example



## Conduction Definitions

- Heat capacity =  $\rho c_p$  (J/m<sup>3</sup>°C)
  - Amount of heat needed to raise a unit volume of material one degree
- Thermal diffusivity =  $\alpha = k/\rho c_p$  (m<sup>2</sup>/s)
  - How fast heat diffuses through a material



## Convection

- Energy transfer due to both
  - molecular motion (diffusion, like conduction) and
  - bulk motion of fluid (motion of gas or liquid)
    - Advection
- Convection=diffusion+advection
- Three kinds
  - Forced convection – external fluid motion
  - Natural (free) convection – motion due to buoyancy effects
  - Latent heat exchange – due to phase change – condensation, boiling (covered in ME 211 but not ME 114)



### Newton's Law of Cooling

$$q = hA(T_s - T_\infty)$$

$$q'' = h(T_s - T_\infty)$$

- h=heat transfer coefficient (W/m<sup>2</sup>°C)
- T<sub>s</sub>=solid surface temperature
- T<sub>∞</sub>=temperature of fluid far from surface
- h=f( )



### Boundary Layer



### Example

- A 0.4 cm x 2 cm computer chip must dissipate 5 W of heat. Air with a heat transfer coefficient of 80 W/m<sup>2</sup>K and a temperature of 20°C blows over the chip. The chip is in danger of overheating if it reaches 90°C. Is the chip in danger? Should you attach a heat sink?



### Thermal Radiation

- Emitted by all matter above 0 Kelvin
- Due to changes in electron configurations
- Requires no medium
- Emissive power of a blackbody (ideal radiator)

$$E_b = \sigma T_s^4$$

- T<sub>s</sub>=surface temp in Kelvin
- σ=Stefan-Boltzmann Constant 5.67x10<sup>-8</sup> W/m<sup>2</sup>K<sup>4</sup>



### Thermal Radiation, Cont.

- ε=emissivity: how efficiently a surface emits compared to a blackbody
- α=absorptivity: percent of incident flux absorbed
- ε,α =f(temp, wavelength, surface condition)

$$E = \epsilon\sigma T_s^4 \quad G_{\text{absorbed}} = \alpha G_{\text{incident}}$$



### Thermal Radiation, cont.

- Special case: ε=α if surface temperatures of all surfaces in an enclosure are close
- Special case: surface completely surrounded by another isothermal surface, no intervening medium

$$q_{\text{rad}} = \text{emitted} - \text{absorbed} = \epsilon\sigma T_s^4 - \alpha\sigma T_{\text{surr}}^4$$

$$= \epsilon\sigma (T_s^4 - T_{\text{surr}}^4) \neq \epsilon\sigma (T_s - T_{\text{surr}})^4$$



## *Total Heat Transfer*

- Only conduction, convection, or radiation can occur or else a combination can occur simultaneously
- $Q_{\text{conv}} + Q_{\text{rad}}$  or  $Q_{\text{cond}} + Q_{\text{rad}}$